	Subclass	ISSUE CLASSIFICATION
09/97 09/97 10/02	Class	ISSUE CLA



PATENT NUMBER			

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APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINED /
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Vishnu Argarwal Scott Meikle

Polishing pads and planarizing machines for mechanical or chemical-mechanical planarization of microelectronic-device substrate assemblies, and methods for making and using such pads and machines

PREPARED AND APPROVED FOR ISSUE

					
ISSUING CLASSIFICATION					
ORIGINAL	CROSS REFERENCE(S)				
CLASS SUBCLASS	CLASS SUBCLASS (ONE SUBCLASS PER BLOCK)				
INTERNATIONAL CLASSIFICATION					
		Continued on Issue Slip Inside File Jacket			

TERMINAL	DRAWINGS			CLAIMS ALLOWED		
DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
	(Assistant Examiner) (Date)			NOTICE OF ALLOWANCE MAILED		
a) The term of this patent subsequent to(date) has been disclaimed.						
b) The term of this patent shall at extend beyond the expration date of U.S Patent. No. 2 3 9 1 8 5 2				ISSUE FEE		
o'O.S Falelli. No. 22 Ja			,	Amount Due	Date Paid	
	(Primary Examiner) (Date)			ISSUE BATCH NUMBER		
C) The terminalmonths of				13305 64	HOMBEIT	
this patent have been disclaimed.	(Legal Instrum	nents Examiner)	(Date)			

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(LABEL AREA)